



2PB710ARL; 2PB710ASL

50 V, 500 mA PNP general-purpose transistors

Rev. 01 — 29 October 2008

Product data sheet

1. Product profile

1.1 General description

PNP general-purpose transistors in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

Table 1. Product overview

Type number ^[1]	Package		NPN complement
	NXP	JEDEC	
2PB710ARL	SOT23	TO-236AB	2PD602ARL
2PB710ASL			2PD602ASL
2PB710ARL/DG	SOT23	TO-236AB	2PD602ARL/DG
2PB710ASL/DG			2PD602ASL/DG

[1] /DG: halogen-free

1.2 Features

- General-purpose transistors
- Two current gain selections
- AEC-Q101 qualified
- Small SMD plastic package

1.3 Applications

- General-purpose switching and amplification

1.4 Quick reference data

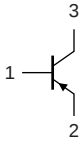
Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	-50	V
I_C	collector current		-	-	-500	mA
h_{FE}	DC current gain	$V_{CE} = -10\text{ V};$ $I_C = -150\text{ mA}$	^[1]			
	h_{FE} group R					
	h_{FE} group S					

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	base		 <i>sym013</i>
2	emitter		
3	collector		

3. Ordering information

Table 4. Ordering information

Type number ^[1]	Package		
	Name	Description	Version
2PB710ARL	-	plastic surface-mounted package; 3 leads	SOT23
2PB710ASL			
2PB710ARL/DG			
2PB710ASL/DG			

[1] /DG: halogen-free

4. Marking

Table 5. Marking codes

Type number	Marking code ^[1]
2PB710ARL	SE*
2PB710ASL	SD*
2PB710ARL/DG	SU*
2PB710ASL/DG	ST*

[1] * = -: made in Hong Kong
* = p: made in Hong Kong
* = t: made in Malaysia
* = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	-60	V
V_{CEO}	collector-emitter voltage	open base	-	-50	V
V_{EBO}	emitter-base voltage	open collector	-	-5	V
I_C	collector current		-	-500	mA
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	-1	A
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms	-	-200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	250	mW
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-55	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	500	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 8. Characteristics

$T_{amb} = 25$ °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	$V_{CB} = -60$ V; $I_E = 0$ A	-	-	-10	nA
		$V_{CB} = -60$ V; $I_E = 0$ A; $T_j = 150$ °C	-	-	-5	μA
I_{EBO}	emitter-base cut-off current	$V_{EB} = -5$ V; $I_C = 0$ A	-	-	-10	nA
h_{FE}	DC current gain	$V_{CE} = -10$ V; $I_C = -500$ mA	[1]	40	-	-
	h_{FE} group R	$V_{CE} = -10$ V; $I_C = -150$ mA	[1]	120	-	240
	h_{FE} group S	$V_{CE} = -10$ V; $I_C = -150$ mA	[1]	170	-	340
V_{CEsat}	collector-emitter saturation voltage	$I_C = -300$ mA; $I_B = -30$ mA	[1]	-	-	-600 mV

Table 8. Characteristics ...continued
 $T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{BEsat}	base-emitter saturation voltage	$I_C = -300\text{ mA};$ $I_B = -30\text{ mA}$	[1]	-	-1.5	V
f_T	transition frequency	$V_{CE} = -10\text{ V};$ $I_C = -50\text{ mA};$ $f = 100\text{ MHz}$				
	h_{FE} group R		120	-	-	MHz
	h_{FE} group S		140	-	-	MHz
C_c	collector capacitance	$V_{CB} = -10\text{ V};$ $I_E = i_e = 0\text{ A};$ $f = 1\text{ MHz}$	-	-	15	pF

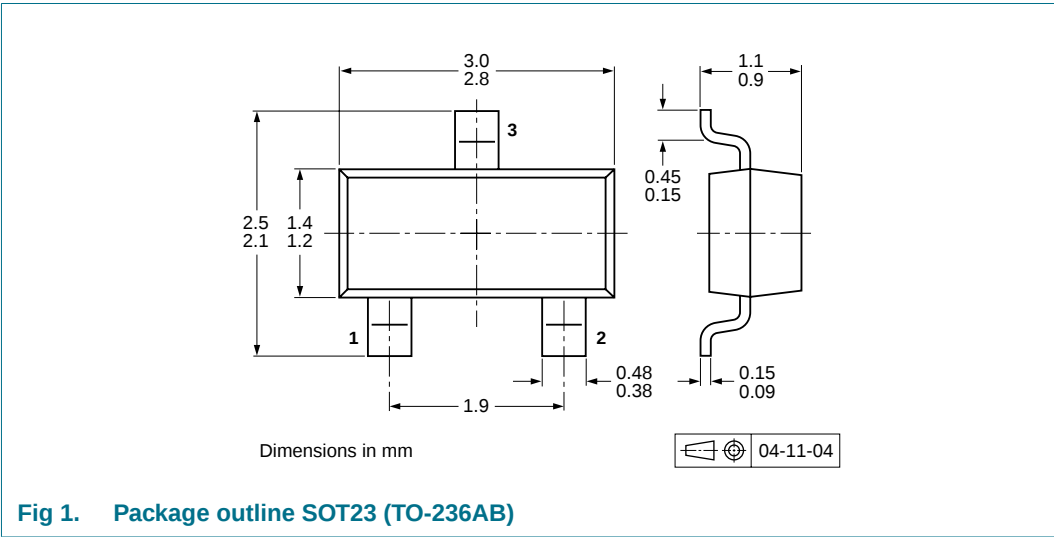
[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

9. Package outline



10. Packing information

Table 9. Packing methods

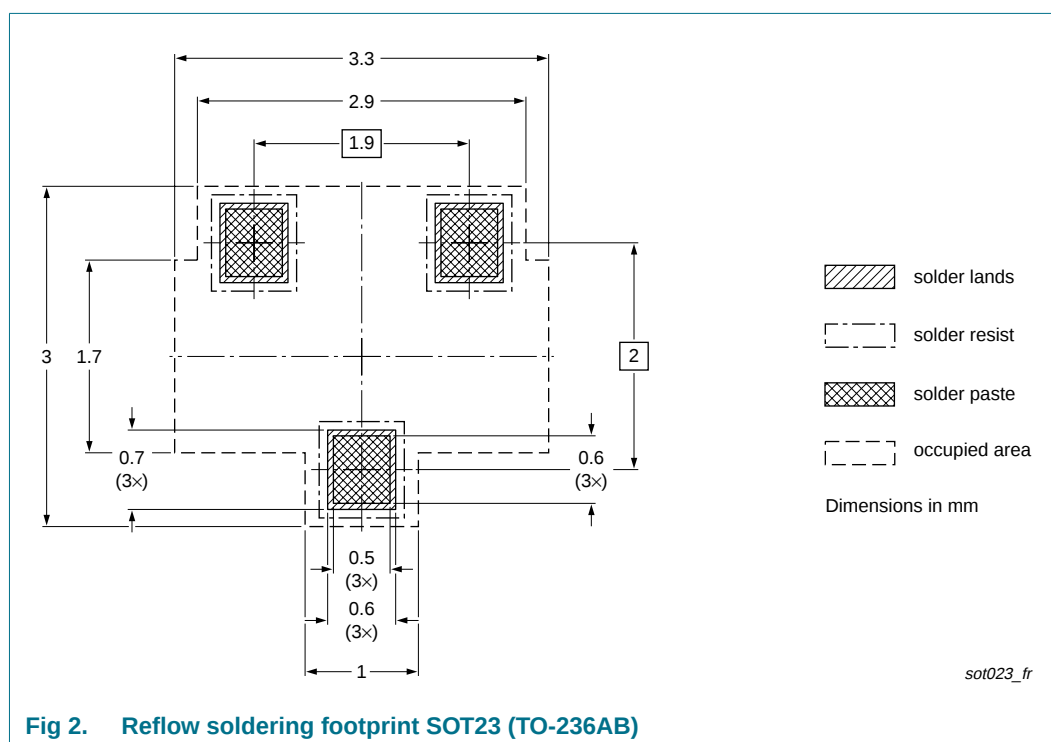
The indicated -xxx are the last three digits of the 12NC ordering code.^[4]

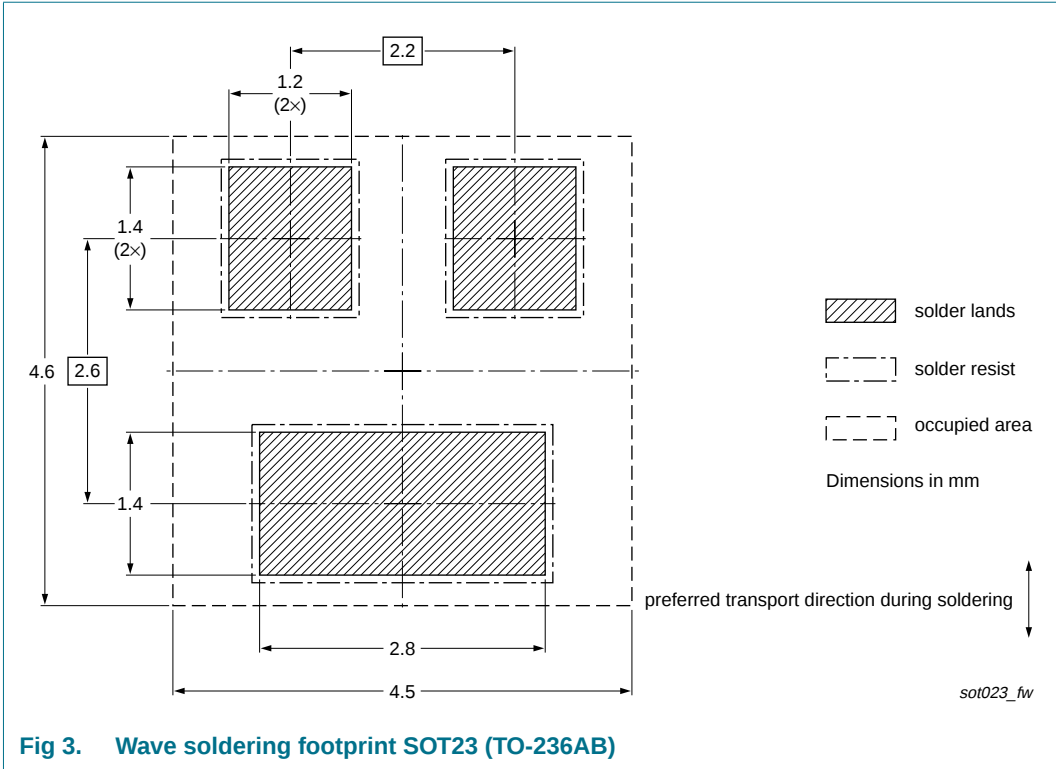
Type number[2]	Package	Description	Packing quantity	
			3000	10000
2PB710ARL	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235
2PB710ASL				
2PB710ARL/DG				
2PB710ASL/DG				

[1] For further information and the availability of packing methods, see [Section 14](#).

[2] /DG: halogen-free

11. Soldering





12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
2PB710AXL_1	20081029	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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15. Contents

1 Product profile 1

1.1 General description..... 1

1.2 Features 1

1.3 Applications 1

1.4 Quick reference data..... 1

2 Pinning information..... 2

3 Ordering information..... 2

4 Marking..... 2

5 Limiting values..... 3

6 Thermal characteristics..... 3

7 Characteristics..... 3

8 Test information..... 4

8.1 Quality information 4

9 Package outline 4

10 Packing information..... 5

11 Soldering 5

12 Revision history..... 7

13 Legal information..... 8

13.1 Data sheet status 8

13.2 Definitions..... 8

13.3 Disclaimers..... 8

13.4 Trademarks..... 8

14 Contact information..... 8

15 Contents 9



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